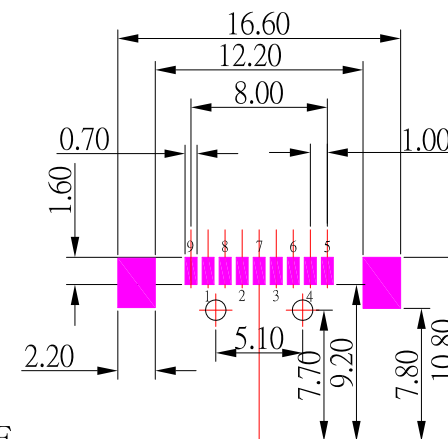
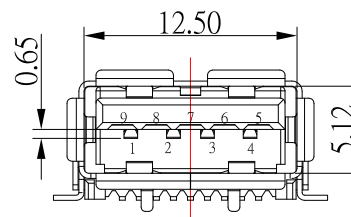
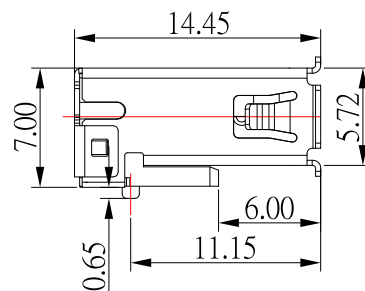
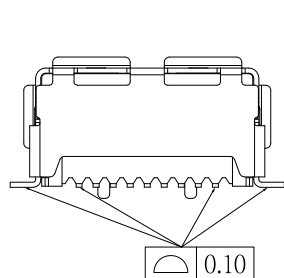
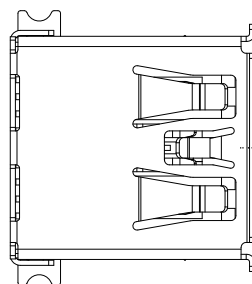
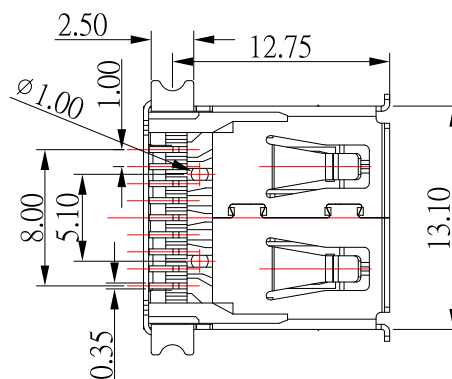




鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

PCB EDGE

RECOMMENDED PCBA LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: Brass

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.5 A

3.2 insulator Resistance:100M Ω Min

3.3 Dielectric Strength: 100V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -40°C ~ +85°C



广东科斯达电子科技有限公司
GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5	± 0.2
	Above 5 ~ 15	± 0.3
	Above 15 ~ 30	± 0.4
	Above 30 ~ 50	± 0.5
	Angle	± 0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	04/11/23
CHECKED BY:	DATE
Jacky Chen	04/11/23
APPROVED BY:	DATE
Tony Kao	04/11/23

DATE _____

04/11/23

CHECKED BY:	DATE
-------------	------

04/11/23

3	MAT'L
3	FINISH
3	SCALE
3	SHEET NO.

TITLE	CONNECTOR
-------	-----------

MODLE

DWG NO.

CELL 1102 FEB 20 1975

D. SUA-110M7B-30xHF-S277

	SIZE
	A4
	VER
	P

[illegible]